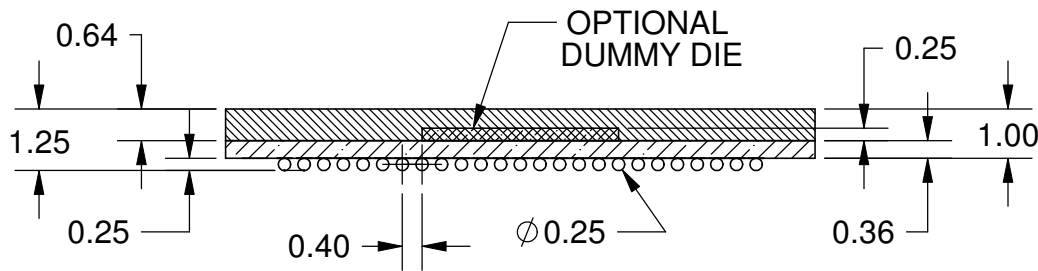
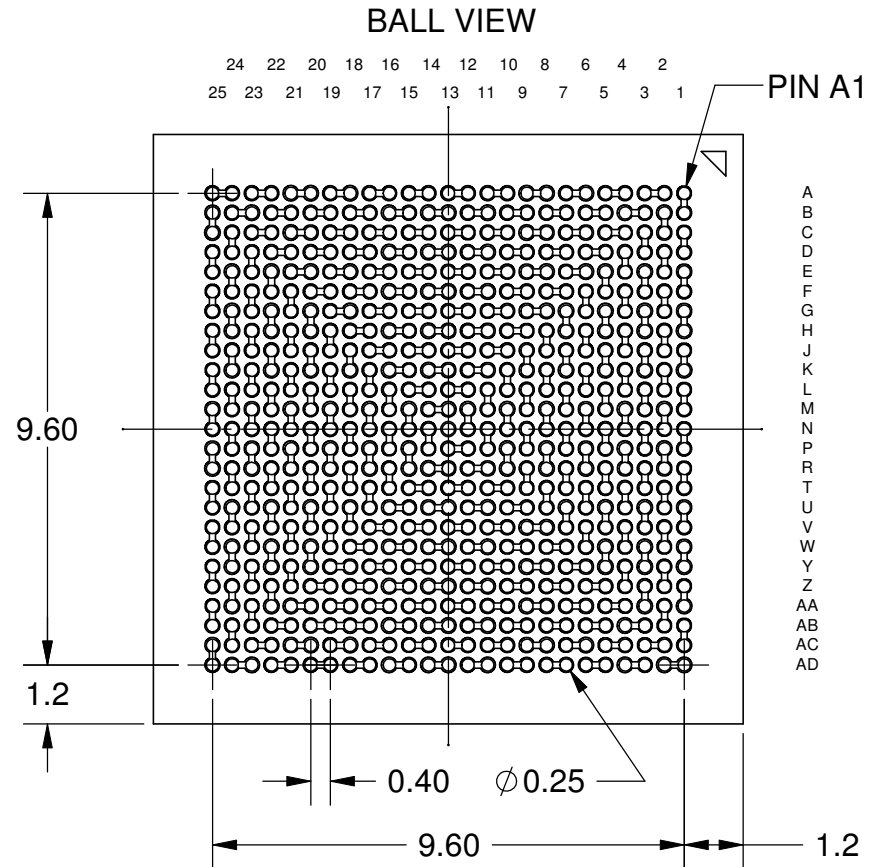
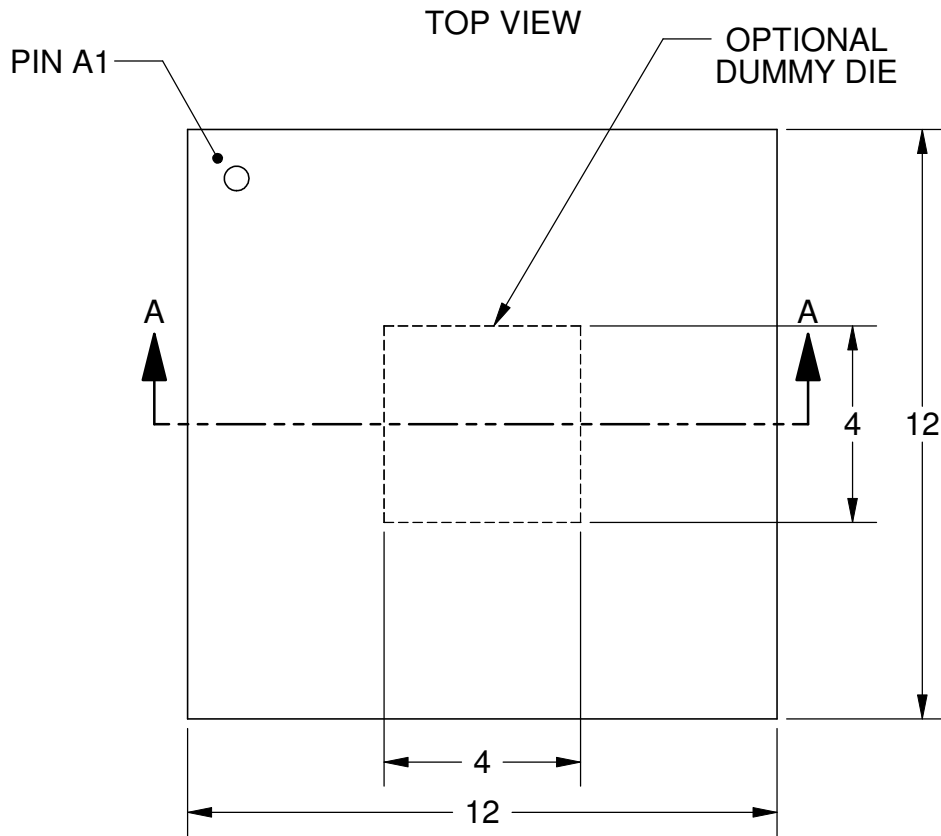


REVISIONS				
DATE	REV.	ECO	DESCRIPTION	APPROVED


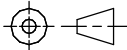


SECTION A-A

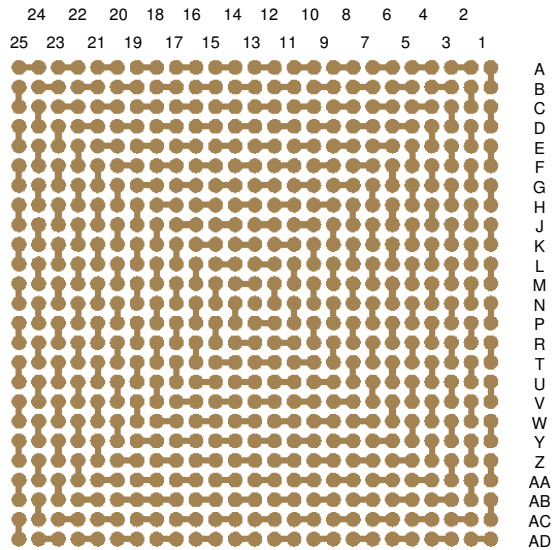
Notes: (Unless Otherwise Specified).

- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- 3) BALL DIAMETER (BEFORE REFLOW): 0.25mm.
- 4) SOLDER MASK DEFINED PAD OPENING: 0.22mm [8.7 MIL].
- 5) PAD Cu DIAMETER: 0.305mm [12 MIL].
- 6) SUBSTRATE MATERIAL: FR4 (ALTERNATE BT).
- 7) DUMMY DIE IS OPTIONAL.
- 8) DAISY CHAIN PATTERN (SEE PAGE 2).
- 9) MSL-3 RECOMMEND BAKING 24 HOURS @ 125C TO REMOVE MOISTURE PRIOR TO SOLDERING TO PC BOARD.

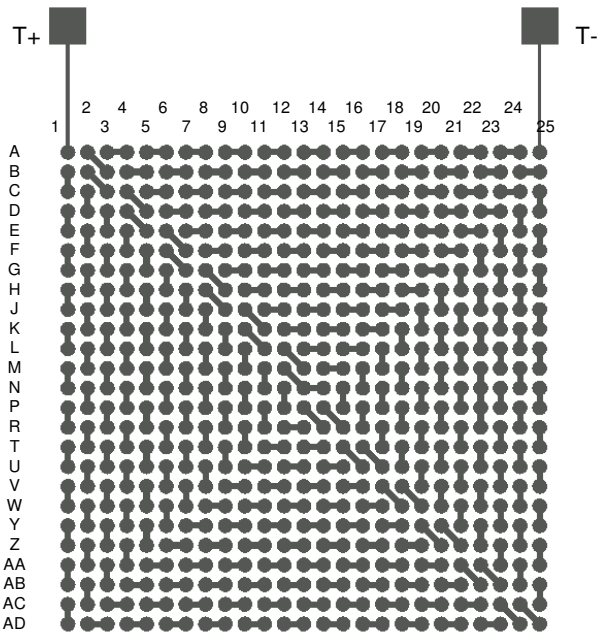
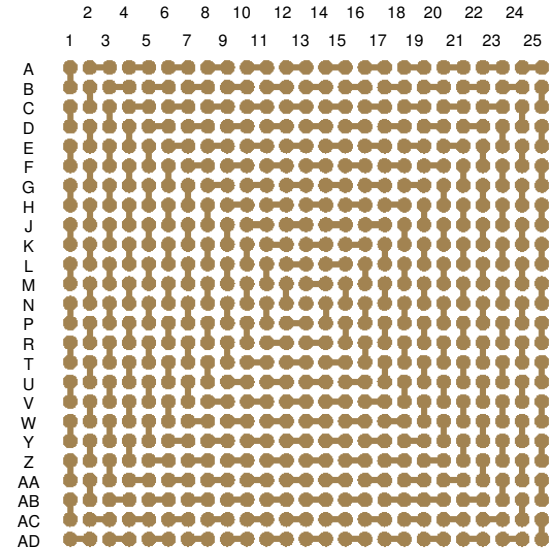
PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	Pb-FREE	RoHS	Si DIE
BGA625T.4C-DC259	Sn96.5/Ag3.0/Cu0.5	YES	YES	NO
BGA625T.4C-DC259D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES
BGA625T.4-DC259	Sn63/Pb37	NO	NO	NO
BGA625T.4-DC259D	Sn63/Pb37	NO	NO	YES

TOLERANCE UNLESS NOTED		APPROVALS		DATE					
X.XX	+/- 0.01	DRAWN J. Hines		9/14/2010					TITLE BGA625T.4-DC259 DAISY CHAIN DUMMY
X.XXX	+/- 0.005	ENG							
X.XXXX	+/- 0.0005	MFG			SCALE		SIZE	DRAWING NO.	REV
ANGLES +/- 0.5° ALL DIMENSIONS IN <input type="checkbox"/> INCHES <input checked="" type="checkbox"/> MILLIMETERS		QA			6.5:1	A	542591	A	
THIRD ANGLE PROJECTION 		CUST			DO NOT SCALE DRAWING				
REVISED					SHEET 1 OF 2				

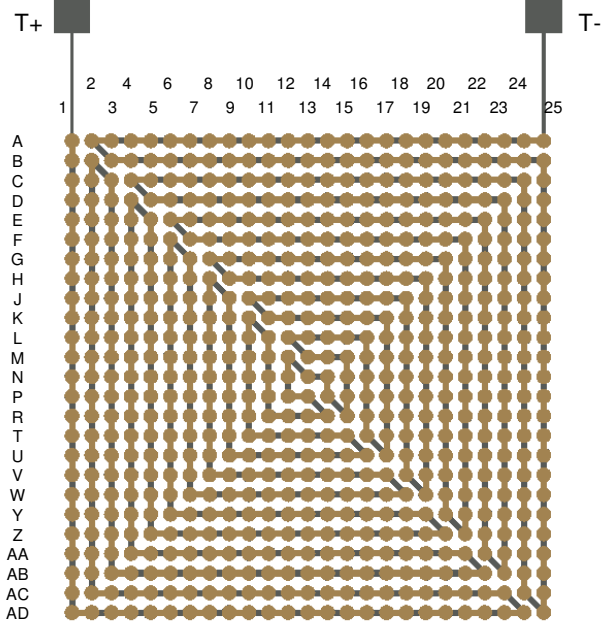
BALL VIEW



BOTTOM SIDE (TOP X-RAY VIEW)



TEST VEHICLE BOARD



AFTER MOUNTING

Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.305mm [12 MIL].
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.127mm [5 MIL].
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING 0.22mm [8.7 MIL].

TopLine ®			
TITLE BGA625T.4-DC259 DAISY CHAIN DUMMY			
SCALE	SIZE	DRAWING NO.	REV
6.5:1	A	542591	A
DO NOT SCALE DRAWING			SHEET 2 OF 2